CMOS Digital Integrated Circuits Silicon Monolithic

74HC594D

1. Functional Description

- 8-Bit Shift Register with Output Register

2. General

The 74HC594D is a high speed 8-BIT SHIFT REGISTER with Output Register fabricated with silicon gate C^2MOS technology.

It achieve the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

The 74HC594D contains an 8-bit static shift register which feeds an 8-bit storage register.

Shift operation is accomplished on the positive going transition of the SCK input. The output register is loaded with the contents of the shift register on the positive going transition of the RCK input. Since RCK and SCK signal are independent, parallel outputs can be held stable during the shift operation. And direct overriding clears ($\overline{SCLR}$ and $\overline{RCLR}$) are provided on both the shift and storage registers.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

3. Features

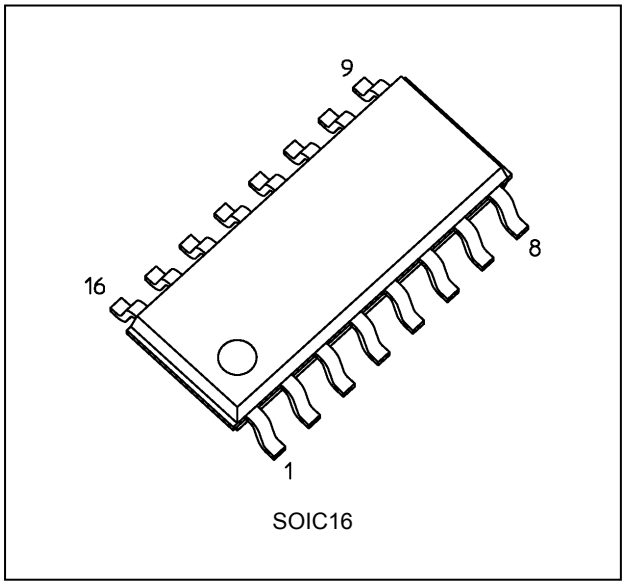
(1) High speed: f_{MAX} = 55 MHz (typ.) at V_{CC} = 5 V

(2) Low power dissipation: I_{CC} = 4.0 μA (max) at T_a = 25°C

(3) Balanced propagation delays: $t_{PLH} \approx t_{PHL}$

(4) Wide operating voltage range: $V_{CC(opr)}$ = 2.0 V to 6.0 V

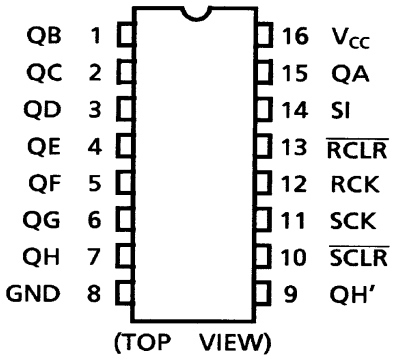
4. Packaging



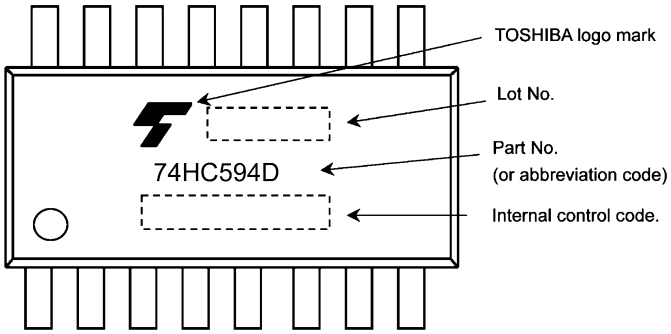
SOIC16

Start of commercial production
2016-04

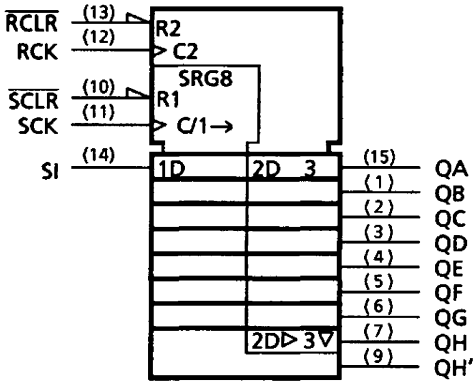
5. Pin Assignment



6. Marking



7. IEC Logic Symbol

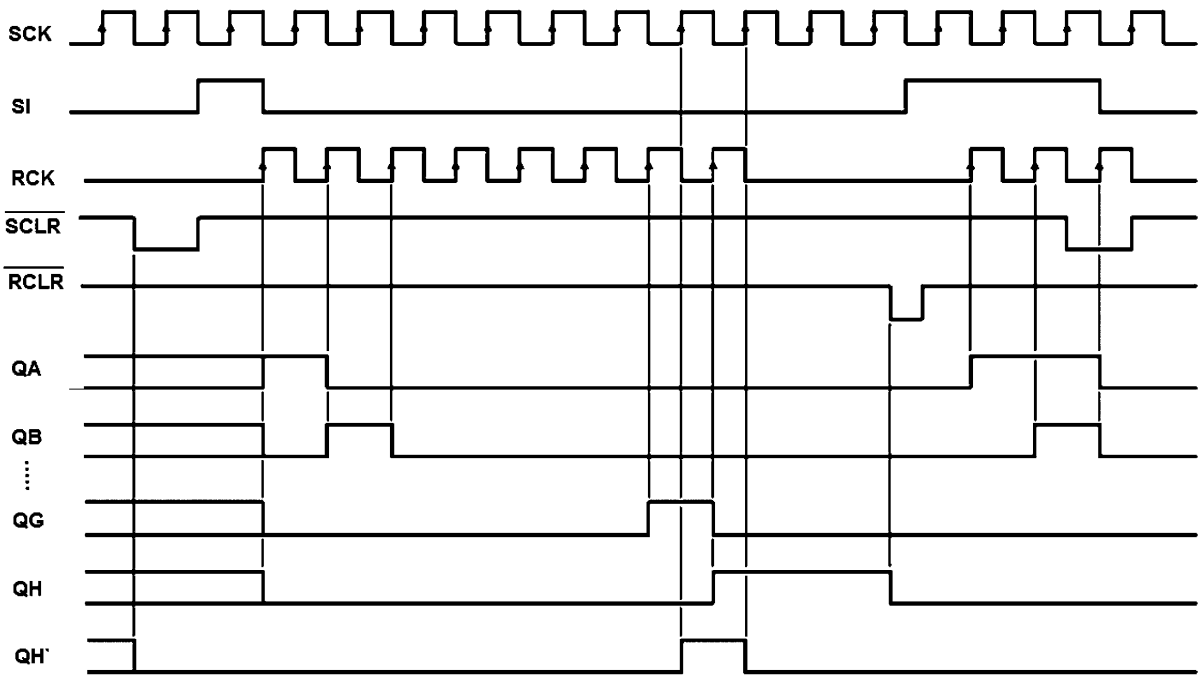


8. Truth Table

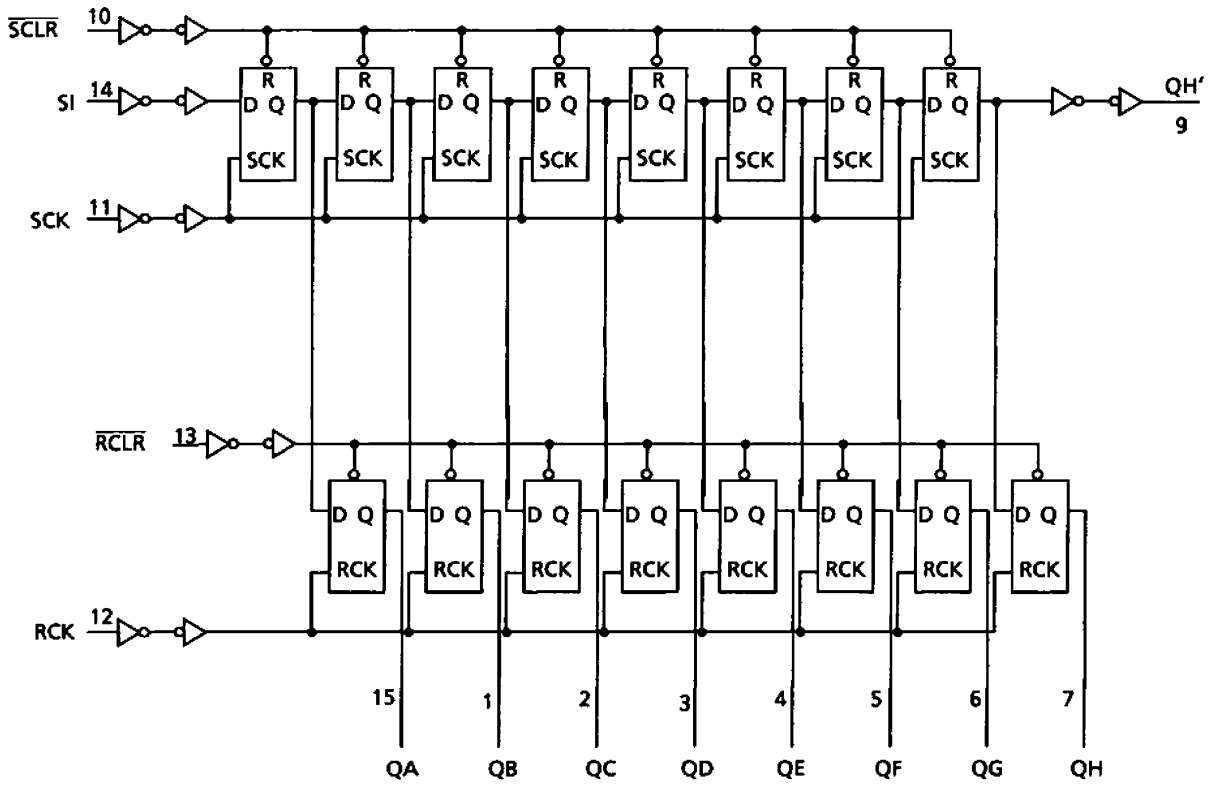
Inputs					Function
SI	SCK	$\overline{SCLR}$	RCK	$\overline{RCLR}$	
X	X	X	X	L	Storage register is cleared.
X	X	L	X	X	Shift register is cleared.
L	↑	H	X	X	First stage of S.R. becomes “L”. Other stages store the data of previous stage, respectively.
H	↑	H	X	X	First stage of S.R. becomes “H”. Other stages store the data of previous stage, respectively.
X	↓	H	X	X	State of S.R. is not changed.
X	X	X	↑	H	S.R. data is stored into storage register.
X	X	X	↓	H	Storage register stage is not changed.

X: Don't care

9. Timing Chart



10. System Diagram



11. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Note	Rating	Unit
Supply voltage	V_{CC}		-0.5 to 7.0	V
Input voltage	V_{IN}		-0.5 to V_{CC} + 0.5	V
Output voltage	V_{OUT}		-0.5 to V_{CC} + 0.5	V
Input diode current	I_{IK}		±20	mA
Output diode current	I_{OK}		±20	mA
Output current (QH')	I_{OUT}		±25	mA
Output current (QA to QH)			±35	
V_{CC}/ground current	I_{CC}		±75	mA
Power dissipation	P_D	(Note 1)	500	mW
Storage temperature	T_{stg}		-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: P_D derates linearly with -8 mW/°C above 85 °C

12. Operating Ranges (Note)

Characteristics	Symbol	Test Condition	Rating	Unit
Supply voltage	V_{CC}	—	2.0 to 6.0	V
Input voltage	V_{IN}	—	0 to V_{CC}	V
Output voltage	V_{OUT}	—	0 to V_{CC}	V
Operating temperature	T_{opr}	—	-40 to 125	°C
Input rise and fall times	t_r,t_f	—	0 to 50	μs

Note: The operating ranges must be maintained to ensure the normal operation of the device.
Unused inputs must be tied to either V_{CC} or GND.

13. Electrical Characteristics

13.1. DC Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition		V_{CC} (V)	Min	Typ.	Max	Unit
High-level input voltage	V_{IH}	—		2.0	1.50	—	—	V
				4.5	3.15	—	—	
				6.0	4.20	—	—	
Low-level input voltage	V_{IL}	—		2.0	—	—	0.50	V
				4.5	—	—	1.35	
				6.0	—	—	1.80	
High-level output voltage	V_{OH}	V_{IN} = V_{IH} or V_{IL}	I_{OH} = -20 μA	2.0	1.9	2.0	—	V
				4.5	4.4	4.5	—	
				6.0	5.9	6.0	—	
High-level output voltage (QH')			I_{OH} = -4 mA	4.5	4.18	4.31	—	
			I_{OH} = -5.2 mA	6.0	5.68	5.80	—	
High-level output voltage (QA to QH)			I_{OH} = -6 mA	4.5	4.18	4.31	—	
			I_{OH} = -7.8 mA	6.0	5.68	5.80	—	
Low-level output voltage	V_{OL}	V_{IN} = V_{IH} or V_{IL}	I_{OL} = 20 μA	2.0	—	0.0	0.1	V
				4.5	—	0.0	0.1	
				6.0	—	0.0	0.1	
Low-level output voltage (QH')			I_{OL} = 4 mA	4.5	—	0.17	0.26	
			I_{OL} = 5.2 mA	6.0	—	0.18	0.26	
Low-level output voltage (QA to QH)			I_{OL} = 6 mA	4.5	—	0.17	0.26	
			I_{OL} = 7.8 mA	6.0	—	0.18	0.26	
Input leakage current	I_{IN}	V_{IN} = V_{CC} or GND		6.0	—	—	±0.1	μA
Quiescent supply current	I_{CC}	V_{IN} = V_{CC} or GND		6.0	—	—	4.0	μA

13.2. DC Characteristics (Unless otherwise specified, T_a = -40 to 85 °C)

Characteristics	Symbol	Test Condition		V_{CC} (V)	Min	Max	Unit
High-level input voltage	V_{IH}	—		2.0	1.50	—	V
				4.5	3.15	—	
				6.0	4.20	—	
Low-level input voltage	V_{IL}	—		2.0	—	0.50	V
				4.5	—	1.35	
				6.0	—	1.80	
High-level output voltage	V_{OH}	V_{IN} = V_{IH} or V_{IL}	I_{OH} = -20 μA	2.0	1.9	—	V
				4.5	4.4	—	
				6.0	5.9	—	
High-level output voltage (QH')			I_{OH} = -4 mA	4.5	4.13	—	
			I_{OH} = -5.2 mA	6.0	5.63	—	
High-level output voltage (QA to QH)			I_{OH} = -6 mA	4.5	4.13	—	
			I_{OH} = -7.8 mA	6.0	5.63	—	
Low-level output voltage	V_{OL}	V_{IN} = V_{IH} or V_{IL}	I_{OL} = 20 μA	2.0	—	0.1	V
				4.5	—	0.1	
				6.0	—	0.1	
Low-level output voltage (QH')			I_{OL} = 4 mA	4.5	—	0.33	
			I_{OL} = 5.2 mA	6.0	—	0.33	
Low-level output voltage (QA to QH)			I_{OL} = 6 mA	4.5	—	0.33	
			I_{OL} = 7.8 mA	6.0	—	0.33	
Input leakage current	I_{IN}	V_{IN} = V_{CC} or GND		6.0	—	±1.0	μA
Quiescent supply current	I_{CC}	V_{IN} = V_{CC} or GND		6.0	—	40.0	μA

13.3. DC Characteristics (Unless otherwise specified, T_a = -40 to 125 °C)

Characteristics	Symbol	Test Condition		V_{CC} (V)	Min	Max	Unit
High-level input voltage	V_{IH}	—		2.0	1.50	—	V
				4.5	3.15	—	
				6.0	4.20	—	
Low-level input voltage	V_{IL}	—		2.0	—	0.50	V
				4.5	—	1.35	
				6.0	—	1.80	
High-level output voltage	V_{OH}	V_{IN} = V_{IH} or V_{IL}	I_{OH} = -20 μA	2.0	1.9	—	V
				4.5	4.4	—	
				6.0	5.9	—	
High-level output voltage (QH')			I_{OH} = -4 mA	4.5	3.7	—	
			I_{OH} = -5.2 mA	6.0	5.2	—	
High-level output voltage (QA to QH)			I_{OH} = -6 mA	4.5	3.7	—	
			I_{OH} = -7.8 mA	6.0	5.2	—	
Low-level output voltage	V_{OL}	V_{IN} = V_{IH} or V_{IL}	I_{OL} = 20 μA	2.0	—	0.1	V
				4.5	—	0.1	
				6.0	—	0.1	
Low-level output voltage (QH')			I_{OL} = 4 mA	4.5	—	0.4	
			I_{OL} = 5.2 mA	6.0	—	0.4	
Low-level output voltage (QA to QH)			I_{OL} = 6 mA	4.5	—	0.4	
			I_{OL} = 7.8 mA	6.0	—	0.4	
3-state output OFF-state leakage current	I_{OZ}	V_{IN} = V_{IH} or V_{IL} V_{OUT} = V_{CC} or GND		6.0	—	±10.0	μA
Input leakage current	I_{IN}	V_{IN} = V_{CC} or GND		6.0	—	±1.0	μA
Quiescent supply current	I_{CC}	V_{IN} = V_{CC} or GND		6.0	—	160.0	μA

13.4. Timing Requirements (Unless otherwise specified, T_a = 25 °C, Input: $t_r = t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Limit	Unit
Minimum pulse width (SCK, RCK)	$t_{w(L)}$,$t_{w(H)}$	—	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum pulse width ($\overline{SCLR}$)	$t_{w(L)}$	—	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum setup time (SI-SCK)	t_S	—	2.0	50	ns
			4.5	10	
			6.0	9	
Minimum setup time (SCK - RCK)	t_S	—	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum setup time ($\overline{SCLR}$ -RCK)	t_S	—	2.0	100	ns
			4.5	20	
			6.0	17	
Minimum hold time	t_h	—	2.0	0	ns
			4.5	0	
			6.0	0	
Minimum removal time ($\overline{SCLR}$)	t_{rem}	—	2.0	50	ns
			4.5	10	
			6.0	9	
Clock frequency	f	—	2.0	6	MHz
			4.5	30	
			6.0	35	

13.5. Timing Requirements (Unless otherwise specified, T_a = -40 to 85 °C, Input: $t_r = t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Limit	Unit
Minimum pulse width (SCK, RCK)	$t_{w(L)}$,$t_{w(H)}$	—	2.0	95	ns
			4.5	19	
			6.0	16	
Minimum pulse width ($\overline{SCLR}$)	$t_{w(L)}$	—	2.0	95	ns
			4.5	19	
			6.0	16	
Minimum setup time (SI-SCK)	t_s	—	2.0	65	ns
			4.5	13	
			6.0	11	
Minimum setup time (SCK - RCK)	t_s	—	2.0	95	ns
			4.5	19	
			6.0	16	
Minimum setup time ($\overline{SCLR}$ -RCK)	t_s	—	2.0	125	ns
			4.5	25	
			6.0	21	
Minimum hold time	t_h	—	2.0	0	ns
			4.5	0	
			6.0	0	
Minimum removal time ($\overline{SCLR}$)	t_{rem}	—	2.0	65	ns
			4.5	13	
			6.0	11	
Clock frequency	f	—	2.0	5	MHz
			4.5	25	
			6.0	28	

13.6. Timing Requirements (Unless otherwise specified, T_a = -40 to 125 °C, Input: $t_r = t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Limit	Unit
Minimum pulse width (SCK, RCK)	$t_{w(L)}$,$t_{w(H)}$	—	2.0	115	ns
			4.5	23	
			6.0	20	
Minimum pulse width ($\overline{SCLR}$)	$t_{w(L)}$	—	2.0	115	ns
			4.5	23	
			6.0	20	
Minimum setup time (SI-SCK)	t_S	—	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum setup time (SCK - RCK)	t_S	—	2.0	115	ns
			4.5	23	
			6.0	20	
Minimum setup time ($\overline{SCLR}$ -RCK)	t_S	—	2.0	150	ns
			4.5	30	
			6.0	26	
Minimum hold time	t_h	—	2.0	0	ns
			4.5	0	
			6.0	0	
Minimum removal time ($\overline{SCLR}$)	t_{rem}	—	2.0	75	ns
			4.5	15	
			6.0	13	
Clock frequency	f	—	2.0	4	MHz
			4.5	20	
			6.0	24	

13.7. AC Characteristics (Unless otherwise specified, C_L = 15 pF, V_{CC} = 5 V, T_a = 25 °C, Input: $t_r = t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Output transition time (QH')	t_{TLH},t_{THL}	—	—	4	8	ns
Propagation delay time (SCK-QH')	t_{PLH},t_{PHL}	—	—	12	21	
Propagation delay time($\overline{SCLR}$-QH')	t_{PHL}	—	—	15	30	
Maximum clock frequency	f_{MAX}	—	35	55	—	MHz

13.8. AC Characteristics (Unless otherwise specified, T_a = 25 °C, Input: $t_r = t_f$ = 6 ns)

Characteristics	Symbol	Note	Test Condition	C_L (pF)	V_{CC} (V)	Min	Typ.	Max	Unit
Output transition time (Qn)	t_{TLH},t_{THL}		—	50	2.0	—	25	60	ns
					4.5	—	7	12	
					6.0	—	6	10	
Output transition time (QH')	t_{TLH},t_{THL}		—	50	2.0	—	30	75	ns
					4.5	—	8	15	
					6.0	—	7	13	
Propagation delay time (SCK-QH')	t_{PLH},t_{PHL}		—	50	2.0	—	45	125	ns
					4.5	—	15	25	
					6.0	—	13	21	
Propagation delay time ($\overline{SCLR}$ -QH')	t_{PHL}		—	50	2.0	—	60	175	ns
					4.5	—	18	35	
					6.0	—	15	30	
Propagation delay time (RCK-Qn)	t_{PLH},t_{PHL}		—	50	2.0	—	60	150	ns
					4.5	—	20	30	
					6.0	—	17	26	
				150	2.0	—	75	190	
					4.5	—	25	38	
					6.0	—	22	32	
Output enable time	t_{PZL},t_{PZH}		R_L = 1 kΩ	50	2.0	—	45	135	ns
					4.5	—	15	27	
					6.0	—	13	23	
				150	2.0	—	60	175	
					4.5	—	20	35	
					6.0	—	17	30	
Output disable time	t_{PLZ},t_{PHZ}		R_L = 1 kΩ	50	2.0	—	30	150	ns
					4.5	—	15	30	
					6.0	—	14	26	
Maximum clock frequency	f_{MAX}		—	50	2.0	6	17	—	MHz
					4.5	30	50	—	
					6.0	35	59	—	
Input capacitance	C_{IN}		—			—	3	—	pF
Power dissipation capacitance	C_{PD}	(Note 1)	—			—	41	—	pF

Note 1: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation.

$I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}$

13.9. AC Characteristics
(Unless otherwise specified, T_a = -40 to 85 °C, Input: $t_r = t_f$ = 6 ns)

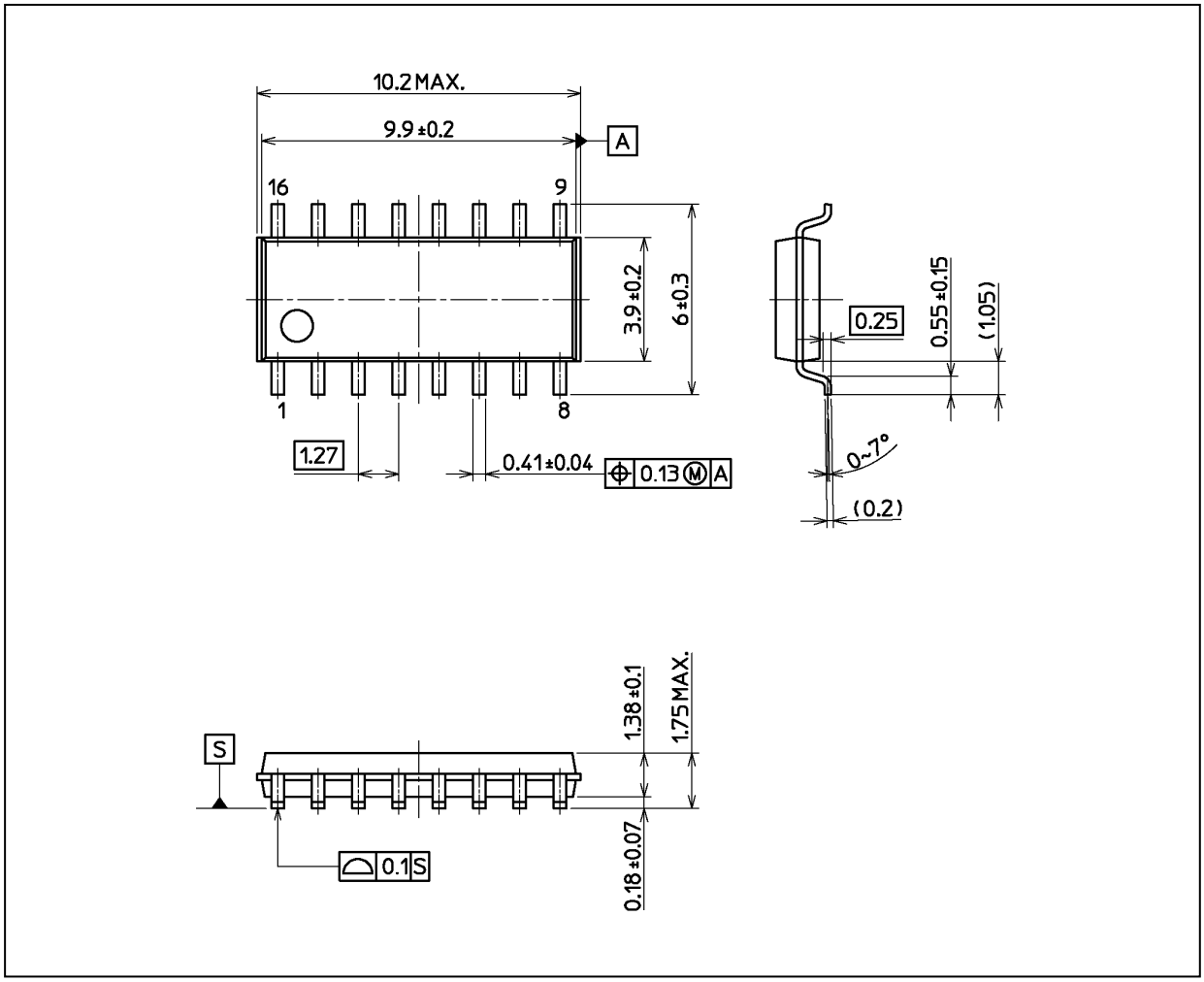
Characteristics	Symbol	Test Condition	C_L (pF)	V_{CC} (V)	Min	Max	Unit
Output transition time (Qn)	t_{TLH},t_{THL}	—	50	2.0	—	75	ns
				4.5	—	15	
				6.0	—	13	
Output transition time (QH')	t_{TLH},t_{THL}	—	50	2.0	—	95	ns
				4.5	—	19	
				6.0	—	16	
Propagation delay time (SCK-QH')	t_{PLH},t_{PHL}	—	50	2.0	—	155	ns
				4.5	—	31	
				6.0	—	26	
Propagation delay time ($\overline{SCLR}$ -QH')	t_{PHL}	—	50	2.0	—	220	ns
				4.5	—	44	
				6.0	—	37	
Propagation delay time (RCK-Qn)	t_{PLH},t_{PHL}	—	50	2.0	—	190	ns
				4.5	—	38	
				6.0	—	32	
			150	2.0	—	240	
				4.5	—	48	
				6.0	—	41	
Output enable time	t_{PZL},t_{PZH}	R_L = 1 kΩ	50	2.0	—	170	ns
				4.5	—	34	
				6.0	—	29	
			150	2.0	—	220	
				4.5	—	44	
				6.0	—	37	
Output disable time	t_{PLZ},t_{PHZ}	R_L = 1 kΩ	50	2.0	—	190	ns
				4.5	—	38	
				6.0	—	33	
Maximum clock frequency	f_{MAX}	—	50	2.0	5	—	MHz
				4.5	25	—	
				6.0	28	—	

13.10. AC Characteristics
(Unless otherwise specified, T_a = -40 to 125 °C, Input: $t_r = t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	C_L (pF)	V_{CC} (V)	Min	Max	Unit
Output transition time (Qn)	t_{TLH},t_{THL}	—	50	2.0	—	90	ns
				4.5	—	18	
				6.0	—	15	
Output transition time (QH')	t_{TLH},t_{THL}	—	50	2.0	—	115	ns
				4.5	—	23	
				6.0	—	20	
Propagation delay time (SCK-QH')	t_{PLH},t_{PHL}	—	50	2.0	—	190	ns
				4.5	—	38	
				6.0	—	32	
Propagation delay time ($\overline{SCLR}$ -QH')	t_{PHL}	—	50	2.0	—	265	ns
				4.5	—	53	
				6.0	—	45	
Propagation delay time (RCK-Qn)	t_{PLH},t_{PHL}	—	50	2.0	—	225	ns
				4.5	—	45	
				6.0	—	38	
			150	2.0	—	285	
				4.5	—	57	
				6.0	—	48	
Output enable time	t_{PZL},t_{PZH}	R_L = 1 kΩ	50	2.0	—	205	ns
				4.5	—	41	
				6.0	—	35	
			150	2.0	—	265	
				4.5	—	53	
				6.0	—	45	
Output disable time	t_{PLZ},t_{PHZ}	R_L = 1 kΩ	50	2.0	—	225	ns
				4.5	—	45	
				6.0	—	38	
Maximum clock frequency	f_{MAX}	—	50	2.0	4	—	MHz
				4.5	20	—	
				6.0	24	—	

Package Dimensions

Unit: mm



Weight: 0.15 g (typ.)

Package Name(s)
Nickname: SOIC16

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